
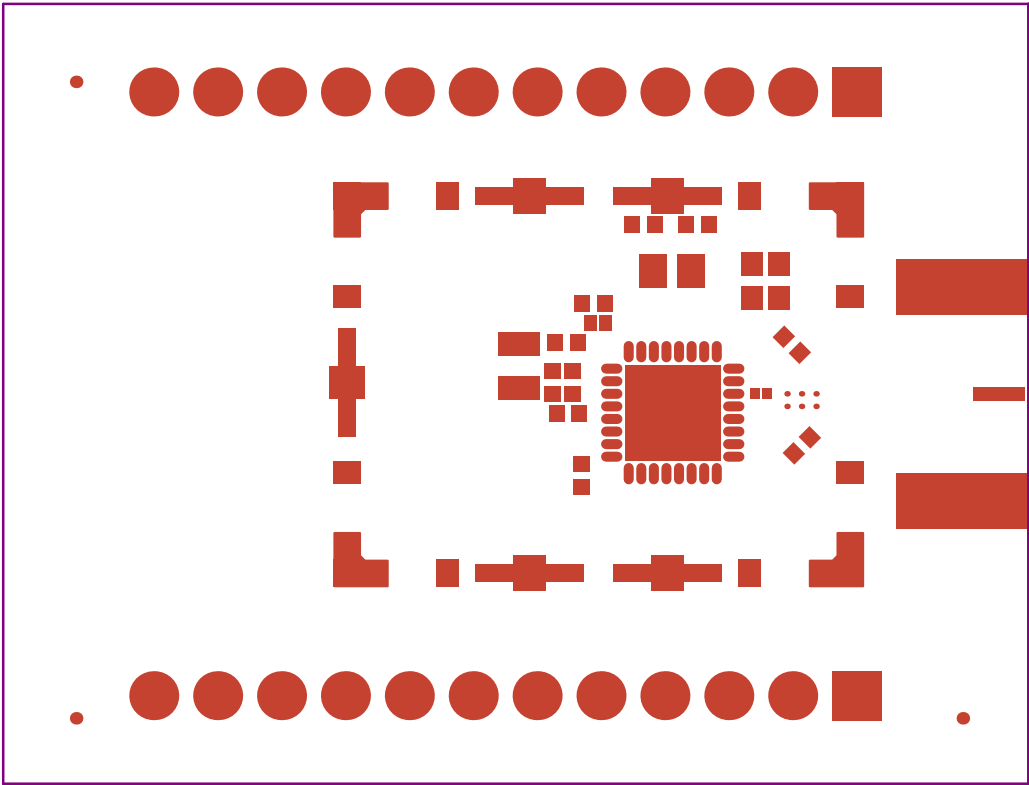

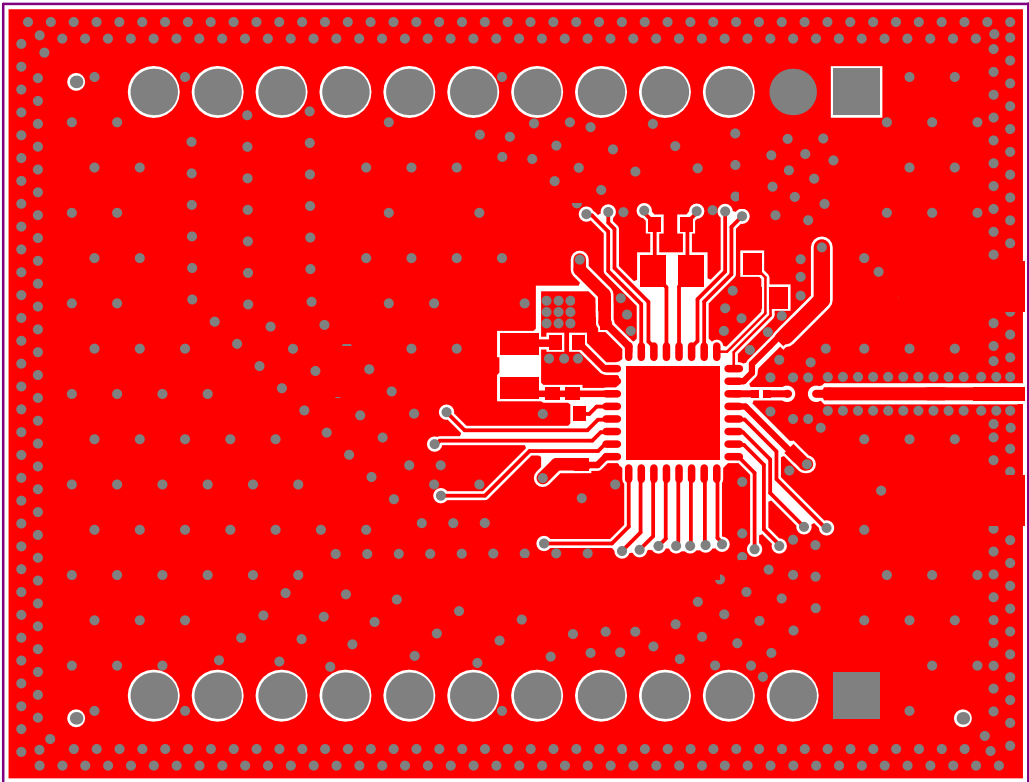



Project: STM32WB05_QFN32_2L_IPD		
Layer: Top Overlay	Gerber: .GTO	
Variant: [No Variations]	Ref: MB2157	
Date: 07 July 2024	Rev: A	




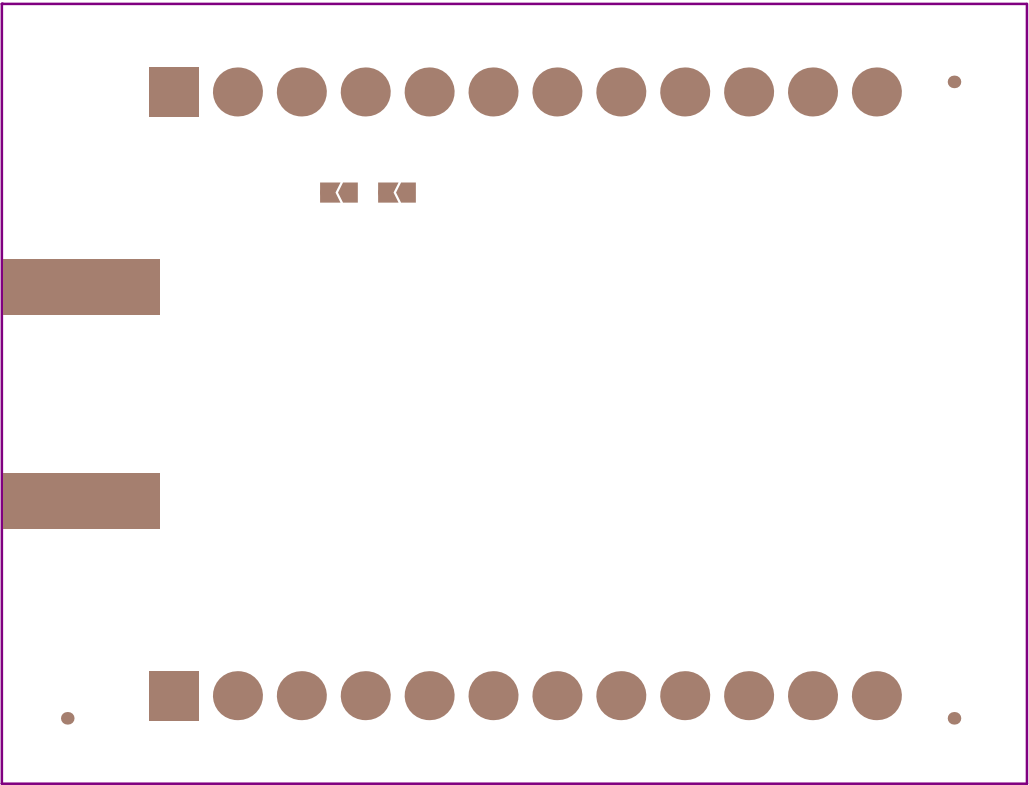
Project: STM32WB05_QFN32_2L_IPD		
Layer: Top Solder	Gerber: .GTS	
Variant: [No Variations]	Ref: MB2157	
Date: 07 July 2024	Rev: A	





Project: STM32WB05_QFN32_2L_IPD		
Layer: Top Layer	Gerber: .GTL	
Variant: [No Variations]	Ref: MB2157	
Date: 07 July 2024	Rev: A	

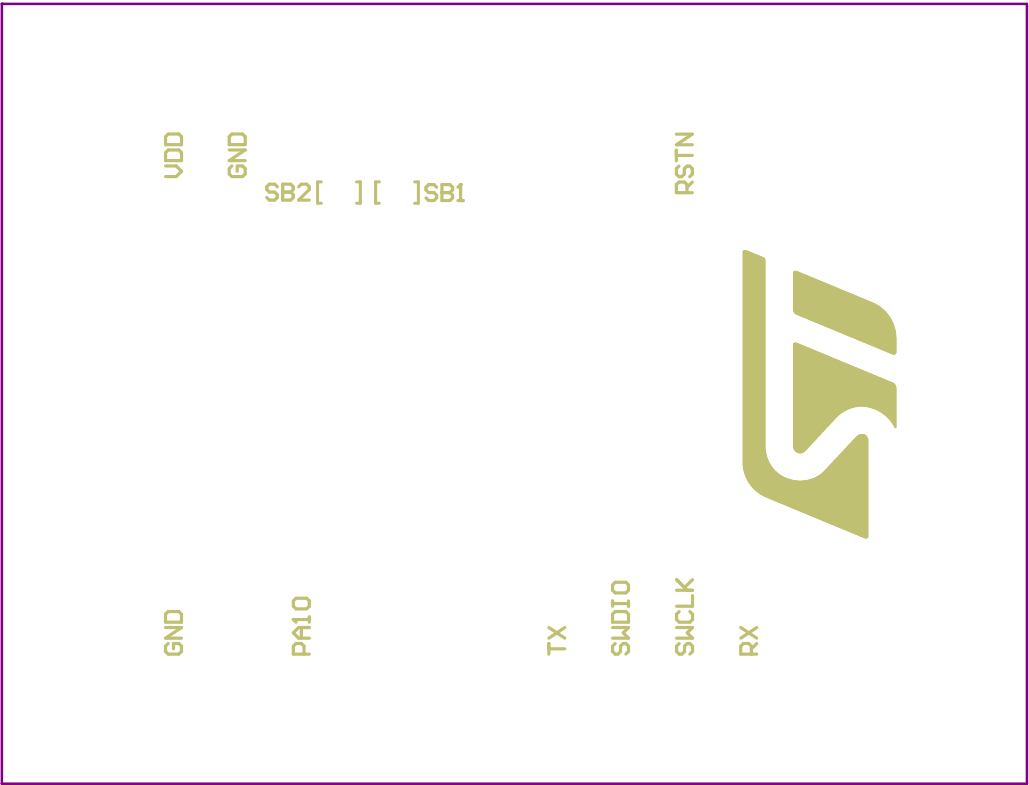


Project: STM32WB05_QFN32_2L_IPD		
Layer: Bottom Layer	Gerber: .GBL	
Variant: [No Variations]	Ref: MB2157	
Date: 07 July 2024	Rev: A	



Project: STM32WB05_QFN32_2L_IPD		
Layer: Bottom Solder	Gerber: .GBS	
Variant: [No Variations]	Ref: MB2157	
Date: 07 July 2024	Rev: A	

Project: STM32WB05_QFN32_2L_IPD		
Layer: Bottom Overlay	Gerber: .GBO	
Variant: [No Variations]	Ref: MB2157	
Date: 07 July 2024	Rev: A	



Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template
□	24	1.000mm (39.37mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	(Mixed)
▽	645	0.200mm (7.87mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	(Mixed)
	669 Total							

PCB SPECIFICATIONS :

A. MATERIAL :

B. MATERIAL FAMILY :

C. SOLDERMASK COLOR :

D. SILKSCREEN COLOR :

E. SURFACE FINISH :

F. IMPEDANCE CONTROL :

G. THROUGH VIA :

H. STACK-UP :

FR-4

N/A

☒ GREEN

☐ BLUE

☐ RED

☐ BLACK

☒ WHITE

☐ YELLOW

☐ BLACK

☒ ENIG

☐ IMMERSION SILVER

☐ IMMERSION TIN

☐ HASL

☐ HASL (PB-FREE)

☐ GOLDEN FINGER

☐ NO

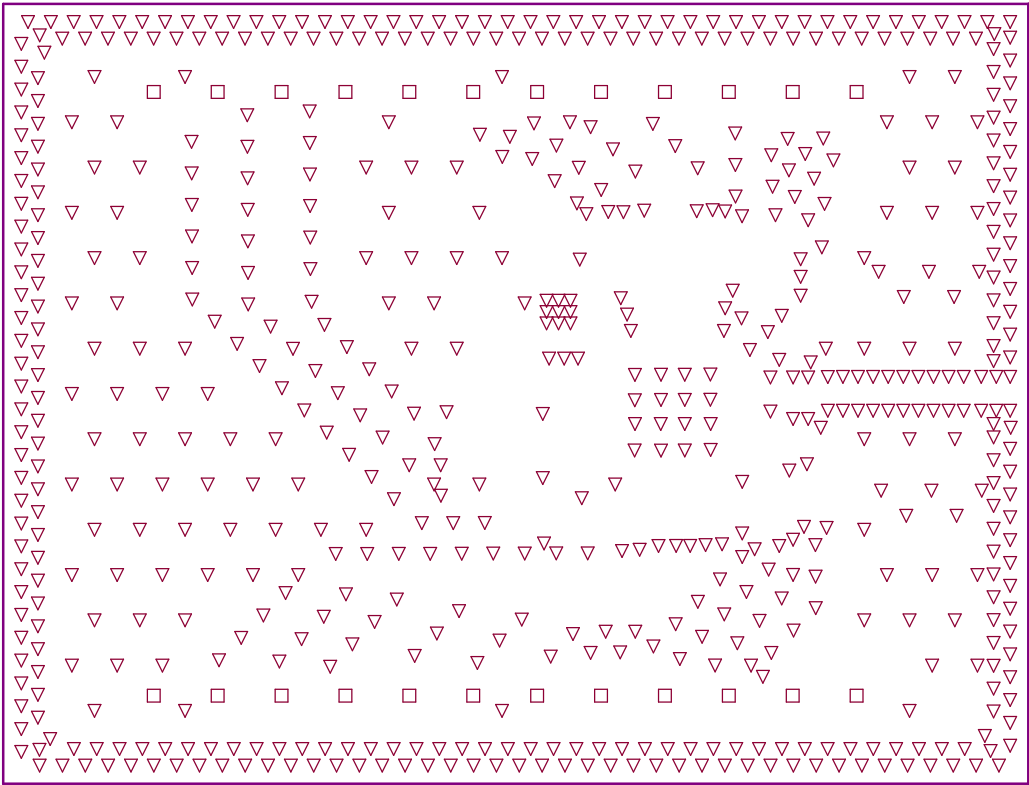
☒ YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)

PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.


PLUG MATERIAL :

☒ SOLDERMASK ☐ NON-CONDUCTIVE EPOXY.

SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.



Layer	Name	Material	Thickness	Constant
	Top Overlay			
	Top Solder	Solder Resist	0.020mm	3.5
1	Top Layer		0.035mm	
	Dielectric 1	VT-47 (2X7628+2116)	0.508mm	4.28
2	Bottom Layer		0.035mm	
	Bottom Solder	Solder Resist	0.020mm	3.5
	Bottom Overlay			

Project: STM32WB05_QFN32_2L_IPD		
Layer: Drill Drawing	Gerber: .DRL	
Variant: [No Variations]	Ref: MB2157	
Date: 07 July 2024	Rev: A	

IMPEDANCE TABLE					
LAYER	TRACE (mm)	SPACING (mm)	IMPEDANCE (Single ended)	IMPEDANCE (Differential)	TOL.
TOP	0.52	0.161	50 ohm	NA	+/- 10%
TOP	0.28	0.128	57 ohm	NA	+/- 10%